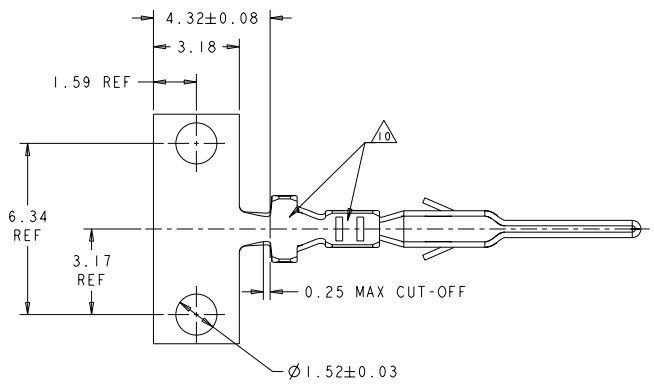
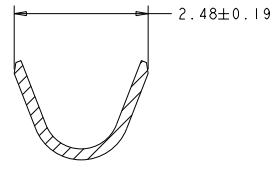
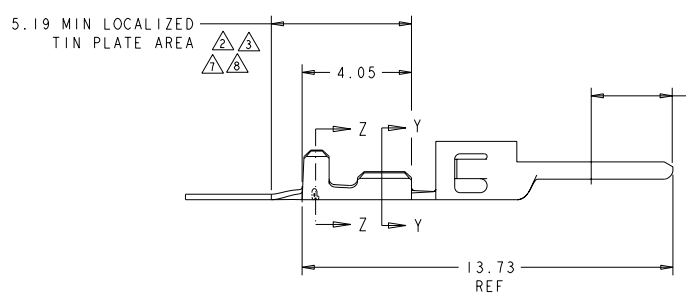


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REV	DESCRIPTION	DATE	BY	APPD
B	REVISED PER 063B-0289-03	24-JUN-03	KW	CJ
C	REVISED PER 063B-1055-04	05-JAN-05	KW	CJ
C1	REVISED PER ECO-05-015508	24-FEB-06	KW	CJ



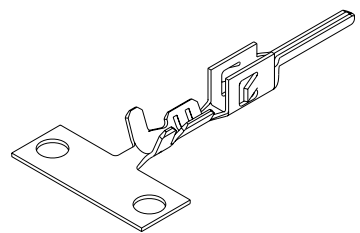
- △ 2.54-6.35 μm MIN BRIGHT TIN/LEAD ENTIRE STOCK OVER 1.27-3.81 μm MIN NICKEL ENTIRE STOCK.
- △ 0.38 μm MIN GOLD IN LOCALIZED GOLD PLATE AREA, 2.54-6.35 μm MIN BRIGHT TIN/LEAD IN LOCALIZED TIN/LEAD PLATE AREA, BOTH OVER 1.27-3.81 μm MIN NICKEL ON ENTIRE STOCK.
- △ 0.76 μm MIN GOLD IN LOCALIZED GOLD PLATE AREA, 2.54-6.35 μm MIN BRIGHT TIN/LEAD IN LOCALIZED TIN/LEAD PLATE AREA, BOTH OVER 1.27-3.81 μm MIN NICKEL ON ENTIRE STOCK.
- 4. WIRE RANGE 26-30 AWG.
- 5. INSULATION RANGE 0.89-1.52
- △ 2.54-6.35 μm MIN BRIGHT TIN ENTIRE STOCK OVER 1.27-3.81 μm MIN NICKEL ENTIRE STOCK.
- △ 0.38 μm MIN GOLD IN LOCALIZED GOLD PLATE AREA, 2.54-6.35 μm MIN BRIGHT TIN IN LOCALIZED TIN PLATE AREA, BOTH OVER 1.27-3.81 μm MIN NICKEL ON ENTIRE STOCK.
- △ 0.76 μm MIN GOLD IN LOCALIZED GOLD PLATE AREA, 2.54-6.35 μm MIN BRIGHT TIN IN LOCALIZED TIN PLATE AREA, BOTH OVER 1.27-3.81 μm MIN NICKEL ON ENTIRE STOCK.
- △ NOTE DELETED.
- △ TIN PLATING THICKNESS INSIDE WIRE AND INSULATION BARRELS TO BE 1.27 μm MIN.



SECTION Y-Y
SCALE 20:1

SECTION Z-Z
SCALE 20:1

△	1-794609-2
△	1-794609-1
△	1-794609-0
△	794609-3
△	794609-2
△	794609-1
FINISH	PART NUMBER



DWN: W. J. RUDY 29AUG2000		Tyco Electronics Harrisburg, PA 17105-3600	
CHK: W. DAVIS 29AUG2000		PLUG CONTACT, CRIMP SNAP 26-30 AWG, MICRO MATE-N-LOK(TM)	
APP: W. DAVIS 29AUG2000		SIZE: A2 CASE CODE: 00779 DRAWING NO: 794609	
MATERIAL: 0.20 THK BRASS		SCALE: 10:1 SHEET 1 OF 1 REV: C1	